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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	4000
Number of Logic Elements/Cells	32000
Total RAM Bits	339968
Number of I/O	450
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-35e-5f672c

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

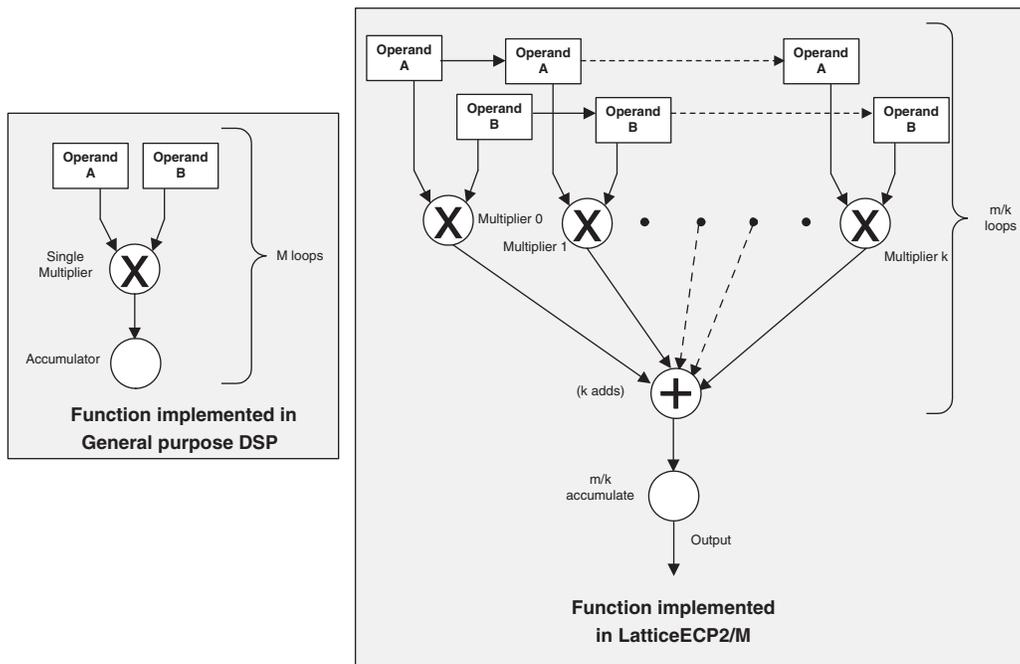
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

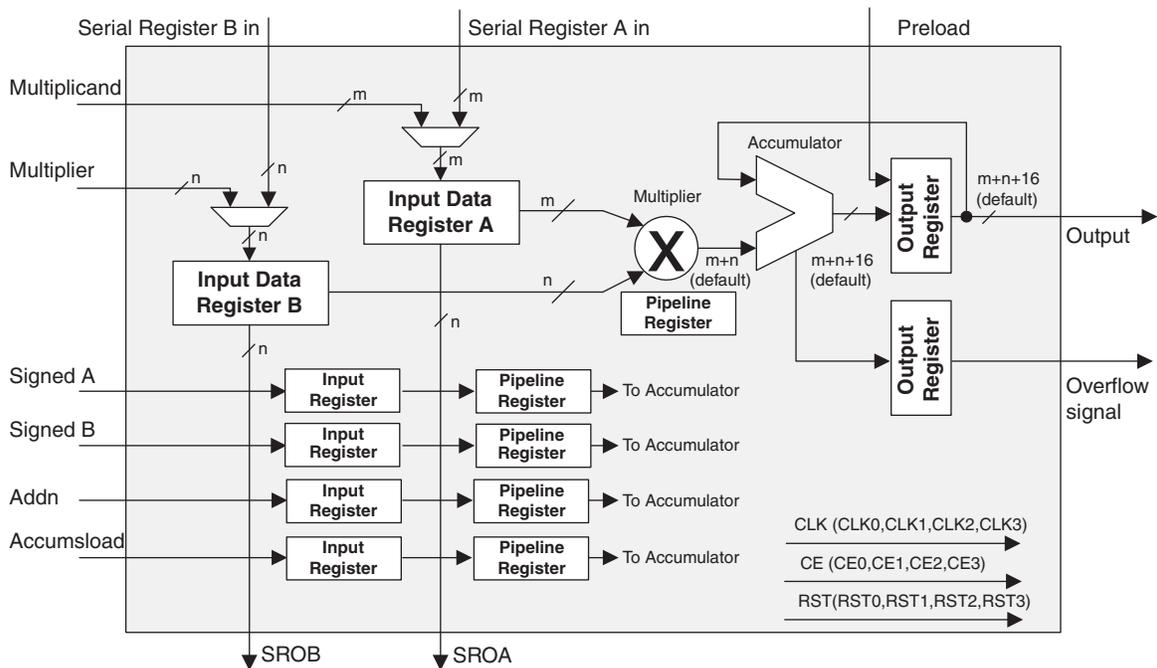
The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

MAC sysDSP Element

In this case, the two operands, A and B, are multiplied and the result is added with the previous accumulated value. This accumulated value is available at the output. The user can enable the input and pipeline registers, but the output register is always enabled. The output register is used to store the accumulated value. The Accumulators in the DSP blocks in the LatticeECP2/M family can be initialized dynamically. A registered overflow signal is also available. The overflow conditions are provided later in this document. Figure 2-24 shows the MAC sysDSP element.

Figure 2-24. MAC sysDSP



LatticeECP2/M DSP Performance

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP2/M family.

Table 2-11. DSP Performance

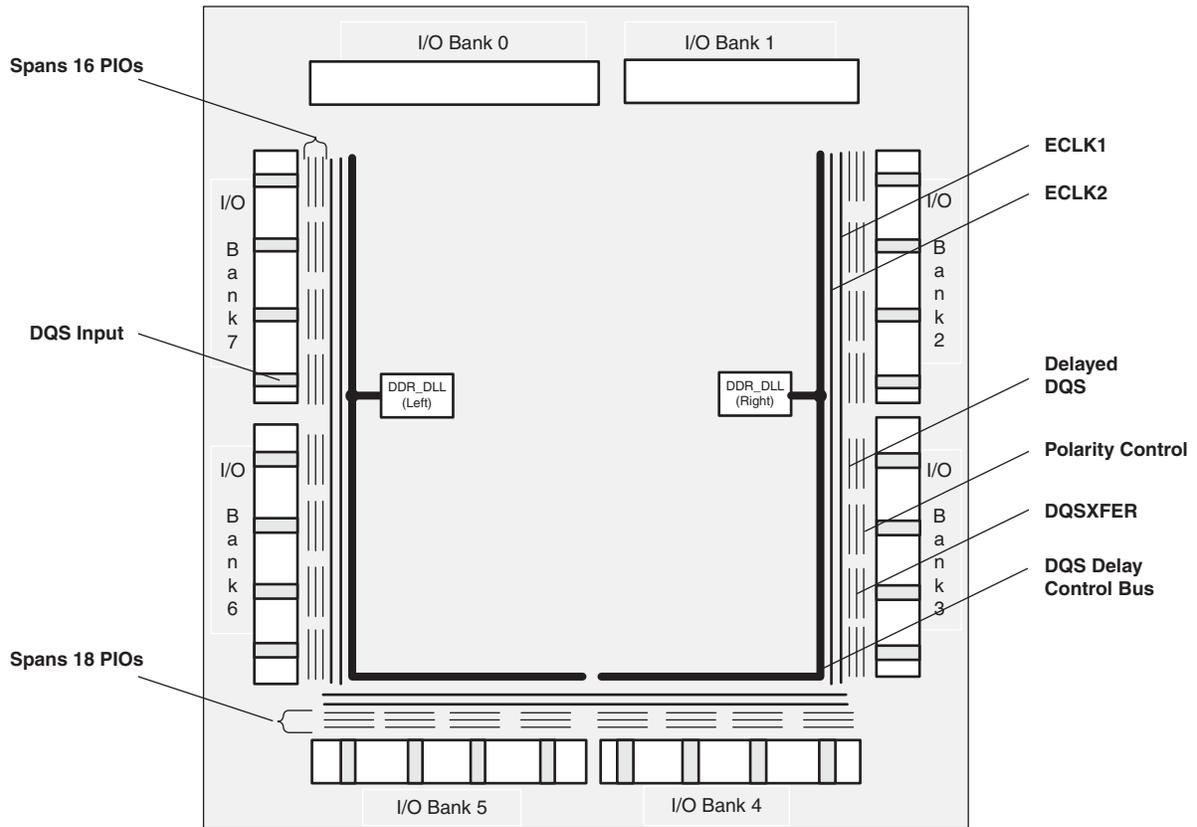
Device	DSP Block	DSP Performance GMAC
ECP2-6	3	3.9
ECP2-12	6	7.8
ECP2-20	7	9.1
ECP2-35	8	10.4
ECP2-50	18	23.4
ECP2-70	22	28.6
ECP2M20	6	7.8
ECP2M35	8	10.4
ECP2M50	22	28.6
ECP2M70	24	31.2
ECP2M100	42	54.6

For further information about the sysDSP block, please see the list of additional technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O buffers as shown in Figure 2-28. The PIO Block supplies the output data (DO) and the tri-state control signal (TO) to the sysI/O buffer and receives input from the buffer. Table 2-12 provides the PIO signal list.

Figure 2-35. Edge Clock, DLL Calibration and DQS Local Bus Distribution



Note: Bank 8 is not shown.

LatticeECP2 Supply Current (Standby)^{1, 2, 3, 4}
Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply Current	ECP2-6	10	mA
		ECP2-12	20	mA
		ECP2-20	30	mA
		ECP2-35	50	mA
		ECP2-50	70	mA
		ECP2-70	100	mA
I _{CCAUX}	Auxiliary Power Supply Current	ECP2-6	24	mA
		ECP2-12	24	mA
		ECP2-20	24	mA
		ECP2-35	24	mA
		ECP2-50	24	mA
		ECP2-70	24	mA
I _{CCGPLL}	GPLL Power Supply Current (per GPLL)	ECP2-35, -50, -70 Only	0.5	mA
I _{CCSPLL}	GPLL Power Supply Current (per SPLL)	ECP2-35, -50, -70 Only	0.5	mA
I _{CCIO}	Bank Power Supply Current (Per Bank)	ECP2-6	2	mA
		ECP2-12	2	mA
		ECP2-20	2	mA
		ECP2-35	2	mA
		ECP2-50	2	mA
		ECP2-70	2	mA
I _{CCJ}	VCCJ Power Supply Current	All Devices	3	mA

1. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a "blank" configuration data file.
5. T_J = 25°C, power supplies at normal voltage.

sys/I/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

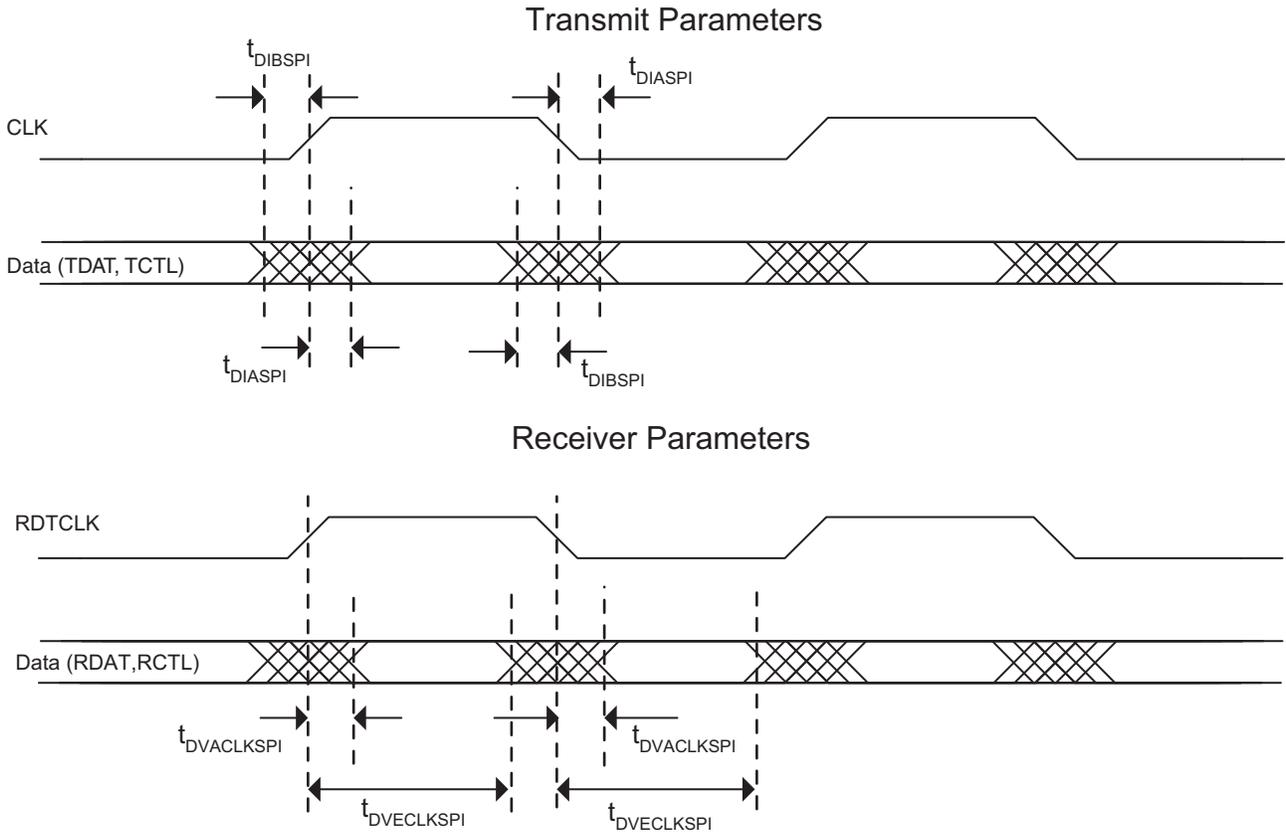
Parameter	Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP} V_{INM}	Input Voltage		0	—	2.4	V
V_{CM}	Input Common Mode Voltage	Half the Sum of the Two Inputs	0.05	—	2.35	V
V_{THD}	Differential Input Threshold	Difference Between the Two Inputs	+/-100	—	—	mV
I_{IN}	Input Current	Power On or Power Off	—	—	+/-10	μ A
V_{OH}	Output High Voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	—	1.38	1.60	V
V_{OL}	Output Low Voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	0.9V	1.03	—	V
V_{OD}	Output Voltage Differential	$(V_{OP} - V_{OM})$, $R_T = 100$ Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} Between High and Low		—	—	50	mV
V_{OS}	Output Voltage Offset	$(V_{OP} + V_{OM})/2$, $R_T = 100$ Ohm	1.125	1.20	1.375	V
ΔV_{OS}	Change in V_{OS} Between H and L		—	—	50	mV
I_{SA}	Output Short Circuit Current	$V_{OD} = 0V$ Driver Outputs Shorted to Ground	—	—	24	mA
I_{SAB}	Output Short Circuit Current	$V_{OD} = 0V$ Driver Outputs Shorted to Each Other	—	—	12	mA

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

For further information about LVPECL, RSDS, MLVDS, BLVDS and other differential interfaces please see the list of additional technical information at the end of this data sheet.

Figure 3-6. SPI4.2 Parameters



DLL Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Typ.	Max.	Units
f_{REF}	Input reference clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{FB}	Feedback clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{CLKOP}^1	Output clock frequency, CLKOP	100	—	500	MHz
f_{CLKOS}^2	Output clock frequency, CLKOS	25	—	500	MHz
t_{PJIT}	Output clock period jitter (clean input)		—	250	ps p-p
t_{CYJIT}	Output clock cycle to cycle jitter (clean input)			250	ps p-p
t_{DUTY}	Output clock duty cycle (at 50% levels, 50% duty cycle input clock, 50% duty cycle circuit turned off, time reference delay mode)	35		65	%
$t_{DUTYTRD}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, time reference delay mode)	40		60	%
$t_{DUTYCIR}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, clock injection removal mode)	40		60	%
t_{SKEW}^3	Output clock to clock skew between two outputs with the same phase setting	—	—	100	ps
t_{PWH}	Input clock minimum pulse width high (at 80% level)	750	—	—	ps
t_{PWL}	Input clock minimum pulse width low (at 20% level)	750	—	—	ps
t_{INSTB}	Input clock period jitter	—	—	+/-250	ps
t_{LOCK}	DLL lock time	18,500	—	—	cycles
t_{RSWD}	Digital reset minimum pulse width (at 80% level)	3	—	—	ns
t_{PA}	Delay step size	16.5	42	59.4	ps
t_{RANGE1}	Max. delay setting for single delay block (144 taps)	2.376	6	8.553	ns
t_{RANGE4}	Max. delay setting for four chained delay blocks	9.504	24	34.214	ns

1. CLKOP runs at the same frequency as the input clock.

2. CLKOS minimum frequency is obtained with divide by 4.

3. This is intended to be a “path-matching” design guideline and is not a measurable specification.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
[LOC]_SQ_VCCIBm	—	Input buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_VCCOBm	—	Output buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_HDOUINm	O	High-speed output, negative channel m
[LOC]_SQ_HDOUOpm	O	High-speed output, positive channel m
[LOC]_SQ_HDINNm	I	High-speed input, negative channel m
[LOC]_SQ_HDINPm	I	High-speed input, positive channel m
[LOC]_SQ_VCCTXm ⁴	—	Transmitter power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.
[LOC]_SQ_VCCR Xm ⁴	—	Receiver power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.

1. These signals are relevant for LatticeECP2M family.
2. m defines the associated channel in the Quad.
3. These signals are defined in Quads [LOC] indicates the corner SERDES Quad is located: ULC (upper left), URC (upper right), LLC (lower left), LRC (lower right).
4. When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given. For more information, refer to TN1159, [LatticeECP2/M Pin Assignment Recommendations](#).
5. There may be SPLs that do not have dedicated I/Os.

LatticeECP2 Pin Information Summary, LFE2-20 and LFE2-35

Pin Type		LFE2-20				LFE2-35	
		208 PQFP	256 fpBGA	484 fpBGA	672 fpBGA	484 fpBGA	672 fpBGA
Single Ended User I/O		131	193	331	402	331	450
Differential Pair User I/O		62	96	165	200	165	224
Configuration	TAP Pins	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7
Non Configuration	Muxed Pins	42	54	60	64	60	68
	Dedicated Pins	3	3	3	3	3	3
VCC		14	7	18	24	16	22
VCCAUX		8	4	16	16	16	16
VCCPLL		0	0	0	0	2	2
VCCIO	Bank0	2	2	4	5	4	5
	Bank1	2	2	4	5	4	5
	Bank2	2	2	4	5	4	5
	Bank3	2	2	4	5	4	5
	Bank4	2	2	4	5	4	5
	Bank5	2	2	4	5	4	5
	Bank6	2	2	4	5	4	5
	Bank7	2	2	4	5	4	5
	Bank8	2	1	2	2	2	2
GND, GND0 to GND7		22	20	60	72	60	72
NC		0	1	8	101	8	102
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	18/9	18/9	50/25	67/33	50/25	67/33
	Bank1	18/9	34/17	46/23	52/26	46/23	52/26
	Bank2	11/5	20/10	34/17	36/18	34/17	48/24
	Bank3	11/5	12/6	22/11	32/16	22/11	42/21
	Bank4	19/9	32/16	46/23	50/25	46/23	54/27
	Bank5	18/9	17/8	46/23	68/34	46/23	68/34
	Bank6	18/8	26/13	40/20	48/24	40/20	58/29
	Bank7	12/6	20/10	33/16	35/17	33/16	47/23
	Bank8	6/2	14/7	14/7	14/7	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0
	Bank2 (Right Edge)	4	5	9	9	9	12
	Bank3 (Right Edge)	3	3	5	8	5	9
	Bank4 (Bottom Edge)	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0
	Bank6 (Left Edge)	6	7	10	12	10	13
	Bank7 (Left Edge)	5	5	8	8	8	11
	Bank8 (Right Edge)	0	0	0	0	0	0

LatticeECP2M Pin Information Summary, LFE2M20 and LFE2M35

Pin Type		LFE2M20		LFE2M35		
		256 fpBGA	484 fpBGA	256 fpBGA	484 fpBGA	672 fpBGA
Single Ended User I/O		140	304	140	303	410
Differential Pair User I/O		70	152	70	151	199
Configuration	TAP Pins	5	5	5	5	5
	Muxed Pins	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7
Non Configuration	Muxed Pins	64	84	60	84	89
	Dedicated Pins	3	3	3	3	3
VCC		6	16	6	16	29
VCCAUX		4	8	4	8	17
VCCPLL		1	4	1	4	8
VCCIO	Bank0	1	4	1	4	5
	Bank1	1	3	1	3	4
	Bank2	2	4	2	4	5
	Bank3	2	4	2	4	5
	Bank4	2	4	2	4	4
	Bank5	2	4	2	4	5
	Bank6	2	4	2	4	5
	Bank7	2	4	2	4	5
	Bank8	1	2	1	2	2
GND, GND0 to GND7		22	57	22	57	80
NC		17	11	17	12	37
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	0/0	36/18	0/0	36/18	63/31
	Bank1	0/0	18/9	0/0	18/9	18/9
	Bank2	14/7	30/15	14/7	30/15	50/25
	Bank3	16/8	36/18	16/8	36/18	43/21
	Bank4	32/16	62/31	32/16	62/31	50/21
	Bank5	20/10	28/14	20/10	28/14	60/30
	Bank6	16/8	40/20	16/8	39/19	52/25
	Bank7	28/14	40/20	28/14	40/20	60/30
	Bank8	14/7	14/7	14/7	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0
	Bank2 (Right Edge)	3	7	3	7	12
	Bank3 (Right Edge)	4	9	4	9	11
	Bank4 (Bottom Edge)	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0
	Bank6 (Left Edge)	4	10	4	10	14
	Bank7 (Left Edge)	7	10	7	10	15
	Bank8 (Right Edge)	0	0	0	0	0

**LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA
 (Cont.)**

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB35B	4	BDQ33	C	PB44B	4	BDQ42	C
W13	PB37A	4	BDQ33	T	PB46A	4	BDQ42	T
GNDIO	GNDIO4	-			GNDIO4	-		
W14	PB37B	4	BDQ33	C	PB46B	4	BDQ42	C
AB18	PB39A	4	BDQ42	T	PB48A	4	BDQ51	T
AB19	PB39B	4	BDQ42	C	PB48B	4	BDQ51	C
Y15	PB41A	4	BDQ42	T	PB50A	4	BDQ51	T
V14	PB40A	4	BDQ42	T	PB49A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
AA15	PB41B	4	BDQ42	C	PB50B	4	BDQ51	C
W15	PB40B	4	BDQ42	C	PB49B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO	-		
AB20	PB43A	4	BDQ42	T	PB52A	4	BDQ51	T
AA16	PB42A	4	BDQS42	T	PB51A	4	BDQS51	T
AB21	PB43B	4	BDQ42	C	PB52B	4	BDQ51	C
AA17	PB42B	4	BDQ42	C	PB51B	4	BDQ51	C
Y16	PB45A	4	BDQ42	T	PB54A	4	BDQ51	T
U15	PB44A	4	BDQ42	T	PB53A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
W16	PB45B	4	BDQ42	C	PB54B	4	BDQ51	C
U16	PB44B	4	BDQ42	C	PB53B	4	BDQ51	C
AA18	PB46A	4	BDQ42	T	PB55A	4	BDQ51	T
AA20	PB46B	4	BDQ42	C	PB55B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO	-		
V16	PB49A	4	BDQ51	T	PB58A	4	BDQ60	T
V17	PB49B	4	BDQ51	C	PB58B	4	BDQ60	C
AA21	PB48A	4	BDQ51	T	PB57A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
Y19	PB51A	4	BDQS51	T	PB60A	4	BDQS60	T
AA22	PB48B	4	BDQ51	C	PB57B	4	BDQ60	C
Y20	PB51B	4	BDQ51	C	PB60B	4	BDQ60	C
Y18	PB50A	4	BDQ51	T	PB59A	4	BDQ60	T
GNDIO	GNDIO4	-			GNDIO4	-		
Y21	PB53A	4	BDQ51	T	PB62A	4	BDQ60	T
Y17	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
Y22	PB53B	4	BDQ51	C	PB62B	4	BDQ60	C
W17	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
U18	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
W18	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
V18	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
GNDIO	GNDIO4	-			GNDIO4	-		
T15	PB55A	4	VREF2_4/BDQ51	T	PB64A	4	VREF2_4/BDQ60	T
T16	PB55B	4	VREF1_4/BDQ51	C	PB64B	4	VREF1_4/BDQ60	C

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E4	PL2A	7	VREF2_7/LDQ6	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
E5	PL2B	7	VREF1_7/LDQ6	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO7	-			GNDIO7	-		
GNDIO	GNDIO7	-			VCCIO	7		
E3	PL10A	7	LDQ14	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
F3	PL10B	7	LDQ14	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
F4	PL11A	7	LDQ14	T	PL13A	7	LDQ16	T
F5	PL11B	7	LDQ14	C	PL13B	7	LDQ16	C
E2	PL12A	7	LDQ14	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO	7		
E1	PL12B	7	LDQ14	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
G6	PL13A	7	LDQ14	T	PL15A	7	LDQ16	T
G7	PL13B	7	LDQ14	C	PL15B	7	LDQ16	C
H4	PL14A	7	LDQS14	T (LVDS)*	PL16A	7	LDQS16	T (LVDS)*
GNDIO	GNDIO7	-			GNDIO7	-		
H5	PL14B	7	LDQ14	C (LVDS)*	PL16B	7	LDQ16	C (LVDS)*
F1	PL15A	7	LDQ14	T	PL17A	7	LDQ16	T
F2	PL15B	7	LDQ14	C	PL17B	7	LDQ16	C
VCCIO	VCCIO7	7			VCCIO	7		
G3	PL16A	7	LDQ14	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
G4	PL16B	7	LDQ14	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
G1	PL17A	7	LDQ14	T	PL19A	7	LDQ16	T
G2	PL17B	7	LDQ14	C	PL19B	7	LDQ16	C
GNDIO	GNDIO7	-			GNDIO7	-		
-	-	-			VCCIO	7		
H6	NC	-			PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T
-	-	-			VCCIO	7		
J6	NC	-			PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C
H3	NC	-			PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T
H2	NC	-			PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C
-	-	-			GNDIO7	-		
-	-	-			VCCIO	7		
H1	PL18A	7	LDQ22		PL37A	7	LDQ41	
J4	PL19A	7	LDQ22	T	PL38A	7	LDQ41	T
J5	PL19B	7	LDQ22	C	PL38B	7	LDQ41	C
VCCIO	VCCIO7	7			VCCIO	7		
J2	PL20A	7	LDQ22	T (LVDS)*	PL39A	7	LDQ41	T (LVDS)*
J1	PL20B	7	LDQ22	C (LVDS)*	PL39B	7	LDQ41	C (LVDS)*
L6	PL21A	7	LDQ22	T	PL40A	7	LDQ41	T
L5	PL21B	7	LDQ22	C	PL40B	7	LDQ41	C
GNDIO	GNDIO7	-			GNDIO7	-		
K3	PL22A	7	LDQS22	T (LVDS)*	PL41A	7	LDQS41	T (LVDS)*
K4	PL22B	7	LDQ22	C (LVDS)*	PL41B	7	LDQ41	C (LVDS)*
K2	PL23A	7	LDQ22	T	PL42A	7	LDQ41	T
VCCIO	VCCIO7	7			VCCIO	7		

**LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA
 (Cont.)**

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N16	VCCIO3	3			VCCIO3	3		
P16	VCCIO3	3			VCCIO3	3		
R14	VCCIO4	4			VCCIO4	4		
T12	VCCIO4	4			VCCIO4	4		
T13	VCCIO4	4			VCCIO4	4		
T14	VCCIO4	4			VCCIO4	4		
R9	VCCIO5	5			VCCIO5	5		
T10	VCCIO5	5			VCCIO5	5		
T11	VCCIO5	5			VCCIO5	5		
T9	VCCIO5	5			VCCIO5	5		
N7	VCCIO6	6			VCCIO6	6		
P7	VCCIO6	6			VCCIO6	6		
P8	VCCIO6	6			VCCIO6	6		
R8	VCCIO6	6			VCCIO6	6		
J8	VCCIO7	7			VCCIO7	7		
K7	VCCIO7	7			VCCIO7	7		
L7	VCCIO7	7			VCCIO7	7		
M7	VCCIO7	7			VCCIO7	7		
P15	VCCIO8	8			VCCIO8	8		
R15	VCCIO8	8			VCCIO8	8		
A22	GND	-			GND	-		
AA19	GND	-			GND	-		
AA4	GND	-			GND	-		
AB1	GND	-			GND	-		
AB22	GND	-			GND	-		
B19	GND	-			GND	-		
B4	GND	-			GND	-		
C14	GND	-			GND	-		
C9	GND	-			GND	-		
D2	GND	-			GND	-		
D21	GND	-			GND	-		
F17	GND	-			GND	-		
F6	GND	-			GND	-		
H10	GND	-			GND	-		
H11	GND	-			GND	-		
H12	GND	-			GND	-		
H13	GND	-			GND	-		
J14	GND	-			GND	-		
J20	GND	-			GND	-		
J3	GND	-			GND	-		
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		

**LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA
 (Cont.)**

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L23	VCCIO2	2			VCCIO2	2		
M17	VCCIO2	2			VCCIO2	2		
M18	VCCIO2	2			VCCIO2	2		
AA23	VCCIO3	3			VCCIO3	3		
R17	VCCIO3	3			VCCIO3	3		
R18	VCCIO3	3			VCCIO3	3		
T23	VCCIO3	3			VCCIO3	3		
V20	VCCIO3	3			VCCIO3	3		
AC16	VCCIO4	4			VCCIO4	4		
AC21	VCCIO4	4			VCCIO4	4		
U15	VCCIO4	4			VCCIO4	4		
V15	VCCIO4	4			VCCIO4	4		
Y18	VCCIO4	4			VCCIO4	4		
AC11	VCCIO5	5			VCCIO5	5		
AC6	VCCIO5	5			VCCIO5	5		
U12	VCCIO5	5			VCCIO5	5		
V12	VCCIO5	5			VCCIO5	5		
Y9	VCCIO5	5			VCCIO5	5		
AA4	VCCIO6	6			VCCIO6	6		
R10	VCCIO6	6			VCCIO6	6		
R9	VCCIO6	6			VCCIO6	6		
T4	VCCIO6	6			VCCIO6	6		
V7	VCCIO6	6			VCCIO6	6		
F4	VCCIO7	7			VCCIO7	7		
J7	VCCIO7	7			VCCIO7	7		
L4	VCCIO7	7			VCCIO7	7		
M10	VCCIO7	7			VCCIO7	7		
M9	VCCIO7	7			VCCIO7	7		
AE25	VCCIO8	8			VCCIO8	8		
V18	VCCIO8	8			VCCIO8	8		
J10	VCCAUX	-			VCCAUX	-		
J11	VCCAUX	-			VCCAUX	-		
J16	VCCAUX	-			VCCAUX	-		
J17	VCCAUX	-			VCCAUX	-		
K18	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
L18	VCCAUX	-			VCCAUX	-		
L9	VCCAUX	-			VCCAUX	-		
T18	VCCAUX	-			VCCAUX	-		
T9	VCCAUX	-			VCCAUX	-		
U18	VCCAUX	-			VCCAUX	-		
U9	VCCAUX	-			VCCAUX	-		
V10	VCCAUX	-			VCCAUX	-		
V11	VCCAUX	-			VCCAUX	-		
V16	VCCAUX	-			VCCAUX	-		
V17	VCCAUX	-			VCCAUX	-		

**LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA
 (Cont.)**

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G19	GND	-			GND	-		
G4	GND	-			GND	-		
H10	GND	-			GND	-		
H13	GND	-			GND	-		
J14	GND	-			GND	-		
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		
K20	GND	-			GND	-		
K3	GND	-			GND	-		
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N20	GND	-			GND	-		
N3	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R13	GND	-			GND	-		
T19	GND	-			GND	-		
T4	GND	-			GND	-		
W16	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
W7	GND	-			GND	-		
Y10	GND	-			GND	-		
Y13	GND	-			GND	-		
D15	NC	-			NC	-		
G14	NC	-			NC	-		
G15	NC	-			NC	-		
D14	NC	-			NC	-		
E15	NC	-			NC	-		
E14	NC	-			NC	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
M23	GND	-		
M8	GND	-		
N14	GND	-		
N15	GND	-		
N16	GND	-		
N17	GND	-		
N27	GND	-		
N4	GND	-		
P11	GND	-		
P13	GND	-		
P14	GND	-		
P15	GND	-		
P16	GND	-		
P17	GND	-		
P18	GND	-		
P20	GND	-		
R10	GND	-		
R11	GND	-		
R13	GND	-		
R14	GND	-		
R15	GND	-		
R16	GND	-		
R17	GND	-		
R18	GND	-		
R20	GND	-		
R21	GND	-		
R24	GND	-		
R7	GND	-		
T10	GND	-		
T11	GND	-		
T13	GND	-		
T14	GND	-		
T15	GND	-		
T16	GND	-		
T17	GND	-		
T18	GND	-		
T20	GND	-		
T21	GND	-		
T24	GND	-		
T7	GND	-		
U11	GND	-		
U13	GND	-		
U14	GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO1	-			GNDIO1	-		
F19	PT59B	1		C	PT68B	1		C
D18	PT59A	1		T	PT68A	1		T
L18	NC	-			PT67B	1		C
K19	NC	-			PT67A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A18	PT57B	1	VREF2_1	C	PT66B	1	VREF2_1	C
B18	PT57A	1	VREF1_1	T	PT66A	1	VREF1_1	T
G18	PT56B	1	PCLKC1_0	C	PT65B	1	PCLKC1_0	C
E18	PT56A	1	PCLKT1_0	T	PT65A	1	PCLKT1_0	T
F18	PT55B	0	PCLKC0_0	C	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G19	PT55A	0	PCLKT0_0	T	PT64A	0	PCLKT0_0	T
H18	PT54B	0	VREF2_0	C	PT63B	0	VREF2_0	C
K18	PT54A	0	VREF1_0	T	PT63A	0	VREF1_0	T
VCCIO	VCCIO0	0			VCCIO0	0		
J18	PT53B	0		C	PT60B	0		C
L17	PT53A	0		T	PT60A	0		T
G17	PT52B	0		C	PT59B	0		C
-	-	-			GNDIO0	-		
J17	PT52A	0		T	PT59A	0		T
H17	PT51B	0		C	PT58B	0		C
-	-	-			VCCIO0	0		
K17	PT51A	0		T	PT58A	0		T
B17	PT50B	0		C	PT57B	0		C
GNDIO	GNDIO0	-			-	-		
A17	PT50A	0		T	PT57A	0		T
D17	PT49B	0		C	PT56B	0		C
VCCIO	VCCIO0	0			-	-		
F17	PT49A	0		T	PT56A	0		T
B16	PT48B	0		C	PT55B	0		C
A16	PT48A	0		T	PT55A	0		T
-	-	-			GNDIO0	-		
-	-	-			VCCIO0	0		
E17	PT47B	0		C	PT52B	0		C
C17	PT47A	0		T	PT52A	0		T
K16	PT46B	0		C	PT51B	0		C
J15	PT46A	0		T	PT51A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
G16	PT45B	0		C	PT50B	0		C
H15	PT45A	0		T	PT50A	0		T
A15	PT44B	0		C	PT49B	0		C
B15	PT44A	0		T	PT49A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
L16	PT43B	0		C	PT48B	0		C
K15	PT43A	0		T	PT48A	0		T
F16	PT42B	0		C	PT47B	0		C
E16	PT42A	0		T	PT47A	0		T
E15	PT41B	0		C	PT46B	0		C

**LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA
 (Cont.)**

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AK12	NC	-			NC	-		
AK24	NC	-			NC	-		
AK25	NC	-			NC	-		
AK26	NC	-			NC	-		
AK4	NC	-			NC	-		
AK9	NC	-			NC	-		
AL11	NC	-			NC	-		
AL12	NC	-			NC	-		
AL34	NC	-			NC	-		
AM10	NC	-			NC	-		
AM11	NC	-			NC	-		
AM13	NC	-			NC	-		
AM25	NC	-			NC	-		
AN10	NC	-			NC	-		
AN11	NC	-			NC	-		
AN12	NC	-			NC	-		
AN13	NC	-			NC	-		
AN24	NC	-			NC	-		
AN25	NC	-			NC	-		
AP11	NC	-			NC	-		
AP12	NC	-			NC	-		
AP24	NC	-			NC	-		
B10	NC	-			NC	-		
B11	NC	-			NC	-		
B12	NC	-			NC	-		
B13	NC	-			NC	-		
B22	NC	-			NC	-		
B23	NC	-			NC	-		
B24	NC	-			NC	-		
B25	NC	-			NC	-		
C10	NC	-			NC	-		
C11	NC	-			NC	-		
C13	NC	-			NC	-		
C22	NC	-			NC	-		
C24	NC	-			NC	-		
C25	NC	-			NC	-		
D1	NC	-			NC	-		
D15	NC	-			NC	-		
D24	NC	-			NC	-		
D34	NC	-			NC	-		
E10	NC	-			NC	-		
E24	NC	-			NC	-		
E25	NC	-			NC	-		
E26	NC	-			NC	-		
E3	NC	-			NC	-		
E31	NC	-			NC	-		
E32	NC	-			NC	-		
E33	NC	-			NC	-		
E34	NC	-			NC	-		

Date	Version	Section	Change Summary
November 2009 (cont.)	03.5 (cont.)	Pinout Information (cont.)	LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 table - corrected values for LFE2M50, 672 fpBGA in Available DDR-Interfaces per I/O Bank.
			Minor corrections in LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA table.
			Minor corrections in LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA table.
			Minor corrections in LFE2M100E/SE Logic Signal Connections: 900 fpBGA table.
		Updated LFE2-6E/SE and LFE2-12E/SE Logical Signal Connections (changed D1/SPIDS to D1).	
		Ordering Information	Updated LatticeECP2M Part Number Description diagram.
March 2010	03.6	DC and Switching Characteristics	Footnote for SED operating frequency added to the sysCONFIG Port Timing Specifications table.
		Pinout Information	Changed Dual Function pin E7 to be D7/SPDI0 in Logic Signal Connections tables. Changed footnote (***) in Logic Signal Connections table.
July 2010	03.7	Architecture	Updated the Typical sysIO Behavior During Power-up text section.
		Pinout Information	Added reference to powerup information.
			Corrected reference to footnote for pins 131 and 132 for the LFE-20E/SE, 208 PQFP.
			Referenced footnote (***) for all D7/SPID0.
			Changed D7*** to D7/SPID0.
All Sections	Corrected *** footnote.		
		All Sections	Included references to Lattice Diamond design software wherever ispLEVER and ispLeverCORE is specified.
April 2011	03.8	DC and Switching Characteristics	DC Electrical Characteristics table: - Added footnote 3 to I_{IH} - Added footnote 2 to I_{IL} , I_{IH} - Updated C1 and C2 typ. and max. data.
			DLL Timing table – Removed line for t_R and t_F
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added footnote to t_{DINIT} .
		Figure 3-18 – Corrected label to be PRGM (not PRGMRJ).	
		Pinout Information	LFE2-12E/SE and LFE-20/SE Logical Signal Connections for 208 PQFP – Corrected Dual Function information for pins 112, 114, 117, 119.
January 2012	03.9	Multiple	Removed references to ispLEVER design software.
		Architecture	Corrected information regarding SED support.
		DC and Switching Characteristics	Added reference to ESD information.
June 2013	04.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.